

SNOS695C - JUNE 1999 - REVISED MARCH 2013

LM6511 180 ns 3V Comparator

Check for Samples: LM6511

FEATURES

- (Typical Unless Otherwise Noted)
- Operates at +2.7V, +3V, +3.3V, +5V
- Low Power Consumption <9.45 mW @ V⁺ = 2.7V (max)
- Fast Response Time of 180 ns

APPLICATIONS

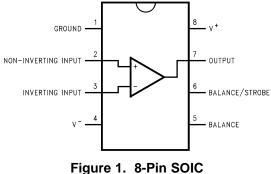
- Portable Equipment
- Cellular Phones
- Digital Level Shifting

DESCRIPTION

The LM6511 voltage comparator is ideal for analogdigital interface circuitry when only a +3V or +3.3V supply is available. The open-collector output permits signal compatibility with a wide variety of digital families: +5V CMOS, +3V CMOS, TTL and so on. Supply voltage may range from 2.7V to 36V between supply voltage leads. The LM6511 operates with little power consumption (P_{diss} < 9.45 mW at V⁺ = +2.7V and V⁻ = 0V).

This voltage comparator offers many features that are available in traditional sub-microsecond comparators: output sync strobe, inputs and output may be isolated from system ground, and wire-ORing. Also, the LM6511 uses the industry-standard, single comparator pinout configuration.

Connection Diagram



See Package Number D



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet. All trademarks are the property of their respective owners.



Absolute Maximum Ratings⁽¹⁾⁽²⁾

Supply Voltage		-0.3 to +36V
Output to Negative Supply Voltage		50V
Ground to Negative Supply Voltage		30V
Differential Input Voltage		±30V
Input Voltage		See ⁽¹⁾
Storage Temperature Range		-65°C to +150°C
Soldering Information:	SOIC Package (Vapor Phase in 60 sec)	215°C
	SOIC Package (Infrared in 15 sec)	220°C
Power Dissipation		500 mW
Output Short Circuit Duration		10s
Junction Temperature		150°C
ESD Rating (C = +100 pF, R = $1.5 \text{ k}\Omega$)	300V	

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating ratings indicate conditions the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.

(2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.

Operating Ratings⁽¹⁾

Supply Voltage		2.5V to 30V
Temperature Range		-40° C ≤ T _J ≤ +85°C
Thermal Resistance (θ_{JA})	SOIC Package	170°C/W

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating ratings indicate conditions the device is intended to be functional, but do not guarantee specific performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed.

DC Electrical Characteristics

Unless otherwise specified, all limits guaranteed for $T_J = 25^{\circ}$ C. **Boldface** limits apply at the temperature extremes. V⁺ = 2.7V, V⁻ = 0V, $50\Omega \le R_1 \le 50k\Omega$, and $I_1 = 1.0$ mA unless otherwise specified

Symbol	Parameter	Conditions	Typical	LM6511I	Units	
-				Limit	(Limits)	
V _{OS}	Offset Voltage	R _S ≤ 50 kΩ ⁽¹⁾	1.5	5	mV	
				8	max	
I _B	Input Bias Current		38	130	nA	
				200	max	
l _{os}	Input Offset Current	$R_S \le 50 \ k\Omega^{(1)}$	1.5	20	nA	
				50	max	
I _S	Positive Supply Current Negative Supply Current		2.7	3.5		
				5	mA	
			1.5	2.0	max	
				2.5		
V _{SAT}	Saturation Voltage	V _{IN} ≤ 10 mV	0.23	0.4	V	
		I _{SINK} = 8 mA		0.4	max	
A _V	Large Signal Voltage Gain	$\Delta V_{OUT} = 2V$	40		V/mV	
CMRR	Common Mode Rejection Ratio		72		dB	
ISTROBE	Strobe ON Current	See ⁽²⁾	2.0	5.0	mA	
					max	

(1) The offset voltage and offset current limits are the maximum values required to drive the output within a volt of either supply with a 1 mA load. Therefore, these parameters define an error band and take into account the worst-case effects of voltage gain and input impedance.

(2) This specification gives the range of current which must be drawn from the strobe pin to ensure the output is properly disabled. Do not short the strobe pin to ground; it should be current driven at 3 mA to 5 mA.

2 Submit Documentation Feedback



DC Electrical Characteristics (continued)

Unless otherwise specified, all limits guaranteed for $T_J = 25^{\circ}$ C. **Boldface** limits apply at the temperature extremes. V⁺ = 2.7V, V⁻ = 0V, $50\Omega \le R_L \le 50k\Omega$, and $I_L = 1.0$ mA unless otherwise specified

Symbol	Parameter	Conditions	Typical	LM6511I	Units	
				Limit	(Limits)	
V _{IN}	Input Voltage Range			0.50	V min	
				V ⁺ - 1.25	V max	
	Output Leakage Current	$V_{IN} \ge 10 \text{ mV}, V_{OUT} = 35V,$ $I_{STROBE} = 3 \text{ mA}$	0.2		nA max	

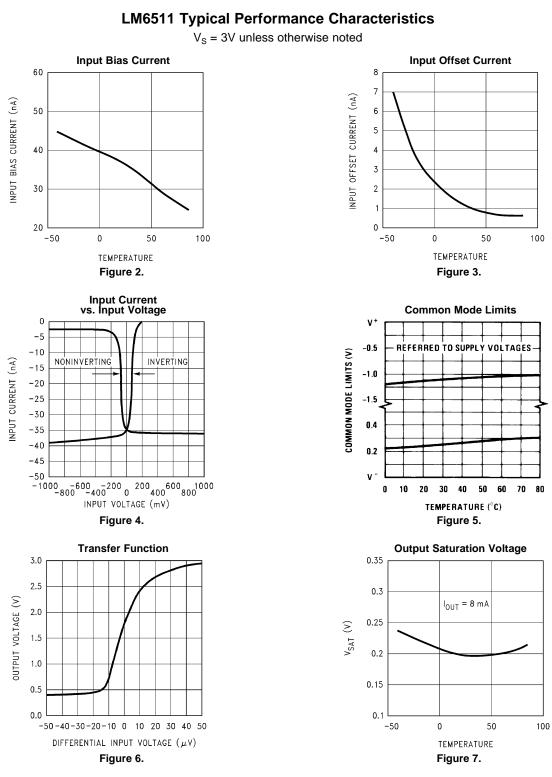
AC Electrical Characteristics

Unless otherwise specified, all limits guaranteed for $T_J = 25^{\circ}$ C. **Boldface** limits apply at the temperature extremes. V⁺ = 2.7V, V⁻ = 0V, $50\Omega \le R_L \le 50k\Omega$, and $I_L = 1.0$ mA unless otherwise specified

Symbol	Parameter	Conditions	Typical	LM6511I	Units
				Limit	(Limits)
T _R	Response Time	See ⁽¹⁾	180		ns

(1) This specification is for a 100 mV input step with a 25 mV overdrive.

SNOS695C-JUNE 1999-REVISED MARCH 2013



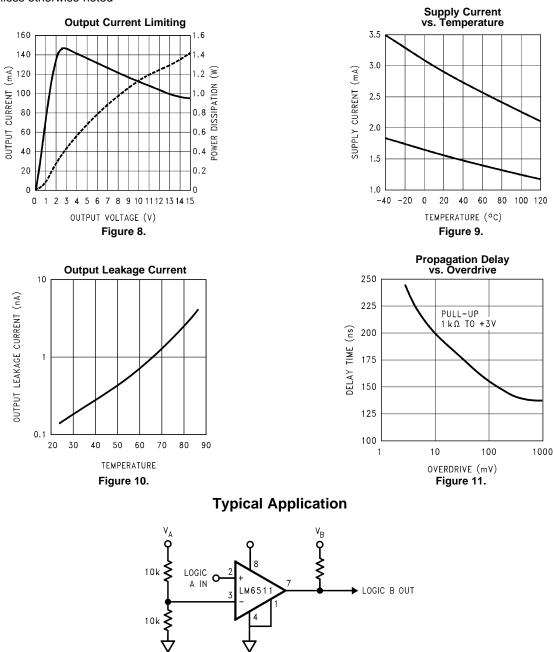
4

Copyright © 1999–2013, Texas Instruments Incorporated



LM6511 Typical Performance Characteristics (continued)

V_S = 3V unless otherwise noted



Notes: Because of the very wide operating and output voltage range, the LM6511 may be used to shift logic levels from 3V to TTL or CMOS to the other way around. By biasing the input to $\frac{1}{2}$ of the input logic supply (V_A), this assures that this input remains within the input voltage range. The pull-up resistor should go to the output logic supply (V_B).

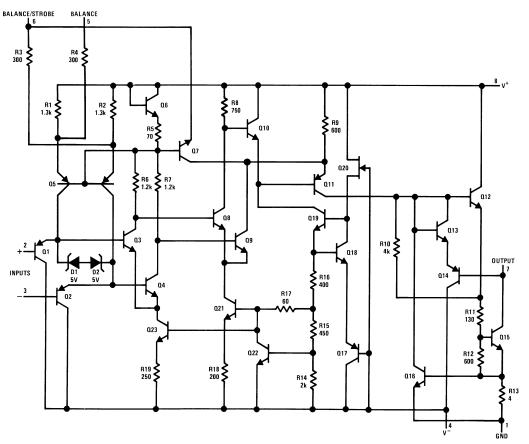
Figure 12. Universal Logic Level Shifter

SNOS695C-JUNE 1999-REVISED MARCH 2013



www.ti.com

Schematic Diagram



Page



www.ti.com

SNOS695C - JUNE 1999-REVISED MARCH 2013

REVISION HISTORY

Changes from	Revision	B (March	2013) to	Revision C	
enangee nem		- (=0.0, 0		



PACKAGING INFORMATION

Orderable Device	Status	Package Type	•	Pins	•	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Top-Side Markings	Samples
	(1)		Drawing		Qty	(2)		(3)		(4)	
LM6511IM	ACTIVE	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 85	LM65 11IM	Samples
LM6511IM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM65 11IM	Samples
LM6511IMX	ACTIVE	SOIC	D	8	2500	TBD	Call TI	Call TI	-40 to 85	LM65 11IM	Samples
LM65111MX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM65 11IM	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

⁽⁴⁾ Multiple Top-Side Markings will be inside parentheses. Only one Top-Side Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Top-Side Marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.



PACKAGE OPTION ADDENDUM

11-Apr-2013

PACKAGE MATERIALS INFORMATION

www.ti.com

Texas Instruments

TAPE AND REEL INFORMATION





QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*A	l dimensions are nominal												
	Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
	LM6511IMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
	LM6511IMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1

TEXAS INSTRUMENTS

www.ti.com

PACKAGE MATERIALS INFORMATION

26-Mar-2013



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM6511IMX	SOIC	D	8	2500	367.0	367.0	35.0
LM6511IMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0

D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have *not* been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		Applications	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	TI E2E Community	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconne	ectivity	

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2013, Texas Instruments Incorporated